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TOTAL AMOUNT OF PAYMENT

(\$) 310.00

Complete if Known		
Application Number	08/915,658	
Filing Date	August 21, 1997	
First Named Inventor	Jigish D. Trivedi	
Examiner Name	G. Peralta	
Group Art Unit	2814	
Attorney Docket No.	MIO 0024 PA	

METHOD OF PAYMENT	FEE CALCULATION (continued)		
The Commissioner is hereby authorized to charge	3. ADDITIONAL FEES	1	
1. indicated fees and credit any overpayments to:	Large Entity Small Entity Fee Fee Fee Fee Fee Paic	, 1	
Deposit Account	Code (\$) Code (\$)	٦١	
Number	105 130 205 65 Surcharge - late filing fee or oath	┤ ┃	
Deposit Account Name	127 50 227 25 Surcharge - late provisional filing fee or cover sheet	-	
Charge Any Additional Fee Required	139 130 139 130 Non-English specification	┨╟	
Under 37 CFR 1.16 and 1.17	147 2,520 147 2,520 For filing a request for ex parte reexamination	-	
Applicant claims small entity status. See 37 CFR 1,27	112 920* 112 920* Requesting publication of SIR prior to	╝	
2. X Payment Enclosed:	Examiner action 113 1,840* 113 1,840* Requesting publication of SIR after Examiner action	4	
A Check Order Order	115 110 215 55 Extension for reply within first month	⊣Ì	
FEE CALCULATION	116 390 216 195 Extension for reply within second month	⊣1	
1. BASIC FILING FEE	117 890 217 445 Extension for reply within third month	4	
Large Entity Small Entity	118 1,390 218 695 Extension for reply within fourth month	41	
Fee Fee Fee Fee Description Code (\$) Code (\$) Fee Paid	400 4 000 209 045 Extension for reply within fifth month		
101 710 201 355 Utility filing fee	119 310 219 155 Notice of Appeal		
106 320 206 160 Design filing fee	120 310 220 155 Filing a brief in support of an appeal	4	
107 490 207 245 Plant filing fee	121 270 221 135 Request for oral hearing	4	
108 710 208 355 Reissue filing fee	138 1,510 138 1,510 Petition to institute a public use proceeding	_	
114 150 214 75 Provisional filing fee	140 110 240 55 Petition to revive - unavoidable	4	
SUBTOTAL (1) (\$) -0-	141 1,240 241 620 Petition to revive - unintentional		
	142 1,240 242 620 Utility issue fee (or reissue)	_	
2. EXTRA CLAIM FEES	143 440 243 220 Design issue fee	\dashv	
Extra Claims below Fee Paid	144 600 244 300 Plant issue fee	_	
Total Claims	122 130 122 130 Petitions to the Commissioner	4	
Claims	123 50 123 50 Petitions related to provisional applications	-	
Multiple Dependent	126 240 126 240 Submission of Information Disclosure Stmt	{	
Large Entity Small Entity Fee Fee Fee Fee Fee Description	581 40 581 40 Recording each patent assignment per property (times number of properties)		
Code (\$) Code (\$) 103 18 203 9 Claims in excess of 20	146 710 246 355 Filing a submission after final rejection 1 (37 CFR § 1.129(a))	_	
102 80 202 40 Independent claims in excess of 3	149 710 249 355 For each additional invention to be		
104 270 204 135 Multiple dependent claim, if not paid	examined (37 CFR § 1.129(b))		
109 80 209 40 ** Reissue independent claims over original patent	179 710 279 355 Request for Continued Examination (RCE)		
110 18 210 9 ** Reissue claims in excess of 20 and over original patent	169 900 169 900 Request for expedited examination of a design application		
SUBTOTAL (2) (\$) -0-	Other fee (specify)		
**or number previously paid, if greater; For Reissues, see above	Reduced by Basic Fining Feet and	=	
SUBMITTED BY	Complete (# applicable)	_	
Name (Pnnt/Type) Timothy W. Hagan	Registration No. (Attorney/Agent) 29,001 Telephone (937)223-2050		
Signature Lating Mr. 47.1.			

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BOX AF Response Under 37 CFR §1.116 Expedited Procedure - Examining Group 2814

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of

Applicant

: Jigish D. Trivedi

Serial No.

: 08/915,658

Filed

: August 21, 1997

Title

: August 21, 1997 : LOW RESISTANCE METAL SILICIDE LOCAL INTERCONNECTS A

METHOD OF MAKING

Docket

: MIO 0024 PA

Examiner

: G. Peralta

Art Unit

: 2814

Assistant Commissioner for Patents

Washington, D.C. 20231

BOX AF

Sir:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on October 31, 2000.

Attorney

Reg. No. 29,001

REQUEST FOR RECONSIDERATION AFTER FINAL REJECTION

This paper is being filed in response to the Office Action mailed August 1, 2000. Reconsideration and reexamination are respectfully requested in light of the remarks below.

REMARKS

Applicant's invention is directed to a local interconnect structure for use in a semiconductor device. The local interconnect is designed to electrically connect at least one of a source, drain, or gate in a field effect transistor. The local interconnect includes a composite structure (see, for example, composite 37 in Figs. 6 and 7) comprising a first refractory metal silicide, a second refractory metal silicide, and an intermetallic compound of the two refractory metals from the refractory metal silicides. In a preferred embodiment of the invention, the refractory metals are titanium and tungsten.

In the most recent Office Action, the Examiner rejected claims 31-34 under 35 USC §102 as anticipated by Okamoto. Okamoto was said to teach, in Fig. 4D, an interconnect structure comprising a composite of a first metal silicide 4 (disclosed as titanium silicide, TiSi2; col. 5, line Serial No. 08/915,658 Atty. Dkt. No. MIO 024 PA (97-0043)

58), a second metal silicide 8 (disclosed as molybdenum silicide, MoSi₂; col. 5, line 59), and "an intermetallic compound 30 comprising metal from said first silicide and metal from said second metal silicide."

Applicant believes that the Examiner has misinterpreted the term "intermetallic compound" as recited in claim 31, and such misinterpretation has led to an incorrect claim construction. Terms in claims must be construed as one skilled in the art would understand them. *Karlin Technology Inc. v. Surgical Dynamics* Inc., 50 USPQ2d 1465 (Fed. Cir. 1999); *Loctite Corp. v. Ultraseal Ltd.*, 228 USPQ 90 (Fed. Cir. 1985) (Claims should be construed as they would be by those skilled in the art.). In the absence of an indication in the specification that a claim term is used in a unique or special way, it will be given its ordinarily understood meaning. *Hazani v. International Trade Commission*, 44 USPQ2d 1359 (Fed. Cir. 1997); *Wright Medical Technology Inc. v. Osteonics Corp.*, 43 USPQ2d 1837 (Fed. Cir. 1997). It is clear from the specification and claims that applicant is using the term "intermetallic compound" in its ordinarily understood sense. See, e.g., specification at page 2, lines 28-29 and page 4, lines 19-20.

By definition, an intermetallic compound is one in which the components are metallic.

The Academic Press Dictionary of Science and Technology defines "intermetallic compound" as:

Metallurgy. An intermediate phase in which the components are metallic; for instance nickel aluminide.

The Encyclopedia Britannica defines "intermetallic compound" as:

any of a class of substances composed of definite proportions of two or more elemental metals, rather than continuously variable proportions (as in solid solutions). The crystal structures and the properties of intermetallic compounds often differ markedly from those of their constituents. In addition to the normal valences of their components, the relative sizes of the atoms and the ration of the total number of valence electrons to the total number of atoms have important effects on the composition of intermetallic compounds.

Okamoto, contrary to the Examiner's assertion, does not teach the formation of an "intermetallic compound" in film 30. Rather, as explicitly taught by Okamoto, film 30 comprises a titanium molybdenum silicide compound, Ti_xMo_ySi_z. See, col. 5, lines 35-41 and 60. Thus, Okamoto

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teaches a ternary silicide film 30, **not** an intermetallic compound as claimed. A ternary silicide does not meet the definition of an intermetallic compound. Accordingly, Okamoto cannot anticipate claims 31-34.

Nor would the teachings of Okamoto render the subject matter of such claims obvious, as Okamoto explicitly teaches the formation of a ternary silicide, not an intermetallic compound. There is nothing in Okamoto which teaches or suggests the formation of an intermetallic compound. Nor, with respect to claim 34, is there any teaching in Okamoto of the use of a tungsten silicide as the second metal silicide in the interconnect.

Also in the most recent Office Action, the Examiner rejected claims 35-40 under 35 USC \$103 as unpatentable over Okamoto in view of Shepard. The Examiner relied upon Okamoto as above with respect to claims 31-34. Shepard was cited for its teaching of a field effect transistor structure having a local interconnect. Even if one were to concede that the teachings of Okamoto and Shepard were properly combinable, the claimed invention still would not result because, as discussed in detail above, Okamoto does not teach or suggest the formation of an intermetallic compound as that term is understood by those skilled in this art. Accordingly, claims 35-40 are patentable for the same reasons that claims 31-34 are patentable.

For all of the above reasons, applicant submits that claims 31-40 are patentable over the cited and applied art. Early notification of allowable subject matter is respectfully solicited.

Respectfully submitted, KILLWORTH, GOTTMAN, HAGAN & SCHAEFF, LLP

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